CUSTOMER PRODUCT SPECIFICATION SHEET

BB02-CL - 1.27mm x 1.27mm (0.05" x 0.05") SMD SOCKET, DUAL ROW, STRAIGHT, 4 to 100 CONTACTS, DUAL ENTRY

SPECIFICATIONS

CURRENT RATING 1 AMP
INSULATOR RESISTANCE 1000 MEGOHMS MIN.
CONTACTS RESISTANCE 20m OHMS MAX.
DIELECTRIC WITHSTANDING AC 300 V
OPERATING TEMPERATURE -40°C TO +105°C
CONTACT MATERIAL PHOSPHOR BRONZE
INSULATOR MATERIAL THERMOPLASTIC, UL 94V-0
PLATING GOLD, TIN, OR SELECTIVE OVER 30-500° NICKEL
SOLDERABILITY: IR REFLOW: 280°C FOR 10 SEC
MANUAL SOLDER: 380°C FOR 3-5 SEC
MATES WITH: BB02-BC BB02-BS BB02-7B
BB02-BD BB02-BY
BB02-BE BB02-BZ
BB02-BK BB02-NE
BB02-BP BB02-NN

RECOMMENDED MATING PIN LENGTH FROM TOP ENTRY IS 4.0MM.

FOR TOP ENTRY  FOR BOTTOM ENTRY

RECOMMENDED PCB BOARD LAYOUT
(TOLERANCE: ±0.05)

HOW TO ORDER

BB02 - C L X X Z - X 0 X - X 0 0 0 0 0

CONTACT PLATING OPTIONS:
K = GOLD FLASH (STANDARD)
A = 10° GOLD ON CONTACT/GOLD FLASH ON TAIL
B = 15° GOLD ON CONTACT/GOLD FLASH ON TAIL
C = 30° GOLD ON CONTACT/GOLD FLASH ON TAIL
T = BRIGHT TIN
M = MATT TIN
D = GOLD FLASH ON CONTACT/BRIGHT TIN ON TAIL

PACKAGING OPTIONS:
3 = TUBE
4 = TUBE + FILM
5 = TUBE + CAP
6 = TAPE & REEL
7 = TAPE & REEL + FILM
8 = TAPE & REEL + CAP

LOCATING PEG OPTIONS:
A = WITH INSIDE PEG
B = WITH OUTSIDE PEG
0 = WITHOUT PEG